



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C110GA3GNND

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 11pF, 25V, ±2%, C0G, 0201

A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>110</u> <u>G</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-l	Samsung Multi-layer Ceramic Capacitor				
② Size	0201 (inch o	code) L: 0.	6 ± 0.03 mm	W:	$0.3 \pm 0.03 \text{ mm}$	
3 Dielectr	ic C0G	8	Inner electrode		Cu	
4 Capacit	ance 11 pF		Termination		Cu	
⑤ Capacit	ance ±2 %		Plating		Sn 100% (Pb Free)	
tolerand	ce	9	Product		Normal	
6 Rated V	oltage 25 V	10	Special		Reserved for future use	
7 Thickne	ess 0.3 ± 0.03	mm 🕦	Packaging		Cardboard Type, 13" reel	

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms		
Q	620 min			
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.		
Resistance	Whichever is Smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	300% of the rated voltage		
Voltage	mechanical breakdown			
Temperature	COG			
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)			
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change :	Bending to the limit (1mm)		
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5℃, 3±0.3sec.		
		(preheating : 80~120℃ for 10~30sec.)		
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	within ±2.5% or ±0.25pF whichever is larger			
	Tan δ, IR : initial spec.			

	Performance	Test condition			
Vibration Test	Capacitance change :	Amplitude : 1.5mm			
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)			
Moisture	Capacitance change :	With rated voltage			
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
	Q: 136.67 min				
	IR : 500Mohm or 25Mohm $\cdot \mu$ F				
	Whichever is Smaller				
High Temperature	Capacitance change :	With 200% of the rated voltage			
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature			
	Q: 302.5 min	1000+48/-0hrs			
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller				
Temperature	Capacitance change :	1 cycle condition			
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25 °C			
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$			
		5 cycle test			

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.